

**IN THE ABSTRACT:**

Please replace page 19 with the following substitute page 19, which includes a rewritten Abstract as follows:

1           Apparatus and methods for testing conductive bumps or target test points  
2 on integrated circuits, ~~comprising~~ A a multiplicity of probes are extended  
3 ~~extending~~ through a support substrate. At least one of the multiplicity of probe  
4 locations include ~~including~~ a second electrically isolated probe such that the test  
5 point is in contact with two probes. One of the two probes provides ~~providing~~ a  
6 voltage to the test point and the second probe sensing the voltage so as to  
7 provide a Kelvin connection.

# **MULTIPLE CONTACT VERTICAL PROBE SOLUTION ENABLING KELVIN CONNECTION BENEFITS FOR CONDUCTIVE BUMP PROBING**

## **Abstract**

Apparatus and methods for testing conductive bumps or target test points on integrated circuits. A multiplicity of probes are extended through a support substrate. At least one of the multiplicity of probe locations include a second electrically isolated probe such that the test point is in contact with two probes. One of the two probes provides a voltage to the test point and the second probe sensing the voltage so as to provide a Kelvin connection.